

HIGH CMR, 10 Mbps OPEN COLLECTOR OUTPUT TYPE
8-PIN DIP HIGH-SPEED PHOTOCOUPLER
FOR CREEPAGE DISTANCE OF 8 mm

–NEPOC Series–

DESCRIPTION

The PS9587, PS9587L1, PS9587L2 and PS9587L3 are optically coupled isolators containing a GaAlAs LED on the input side and a photo diode and a signal processing circuit on the output side on one chip.

The PS9587L1 and PS9587L2 are designed specifically for long creepage-distance as well as high common mode transient immunity (CMR) and high speed digital output type. Consequently, they are suitable for high speed logic interface that needs long creepage-distance (8 mm) on mounting.

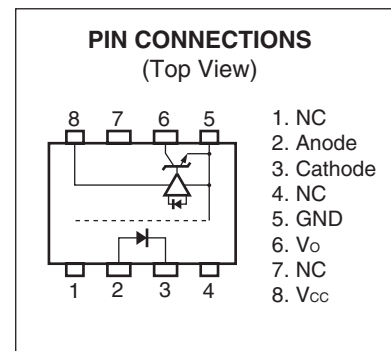
The PS9587L1 is lead bending type for long creepage distance.

The PS9587L2 is lead bending type for long creepage distance (Gull-wing) for surface mount.

The PS9587L3 is lead bending type (Gull-wing) for surface mounting.

FEATURES

- Long creepage distance (8 mm MIN.: PS9587L1, PS9587L2)
- High common mode transient immunity (CMH, CML = ±15 kV/μs MIN.)
- High isolation voltage (BV = 5 000 Vr.m.s.)
- High-speed response (10 Mbps)
- Pulse width distortion (|t_{PHL} – t_{PLH}| = 10 ns TYP.)
- Open collector output
- Ordering number of tape product: PS9587L2-E3: 1 000 pcs/reel
: PS9587L3-E3: 1 000 pcs/reel
- Pb-Free product
- Safety standards
 - UL approved: File No. E72422
 - CSA approved: No. CA 101391
 - BSI approved: No. 8937, 8938
 - SEMKO approved: No. 615433
 - NEMKO approved: No. P06207243
 - DEMKO approved: No. 314091
 - FIMKO approved: No. FI 22827
 - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)



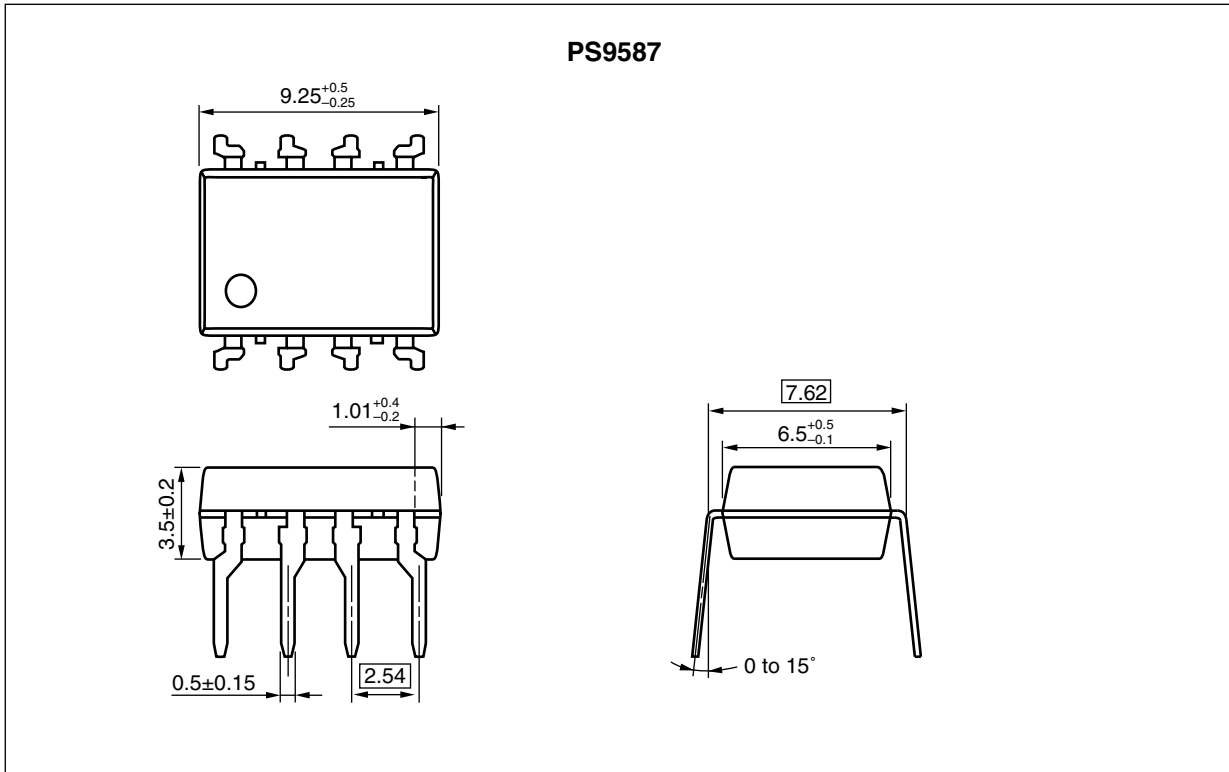
APPLICATIONS

- FA Network
- Measurement equipment
- PDP

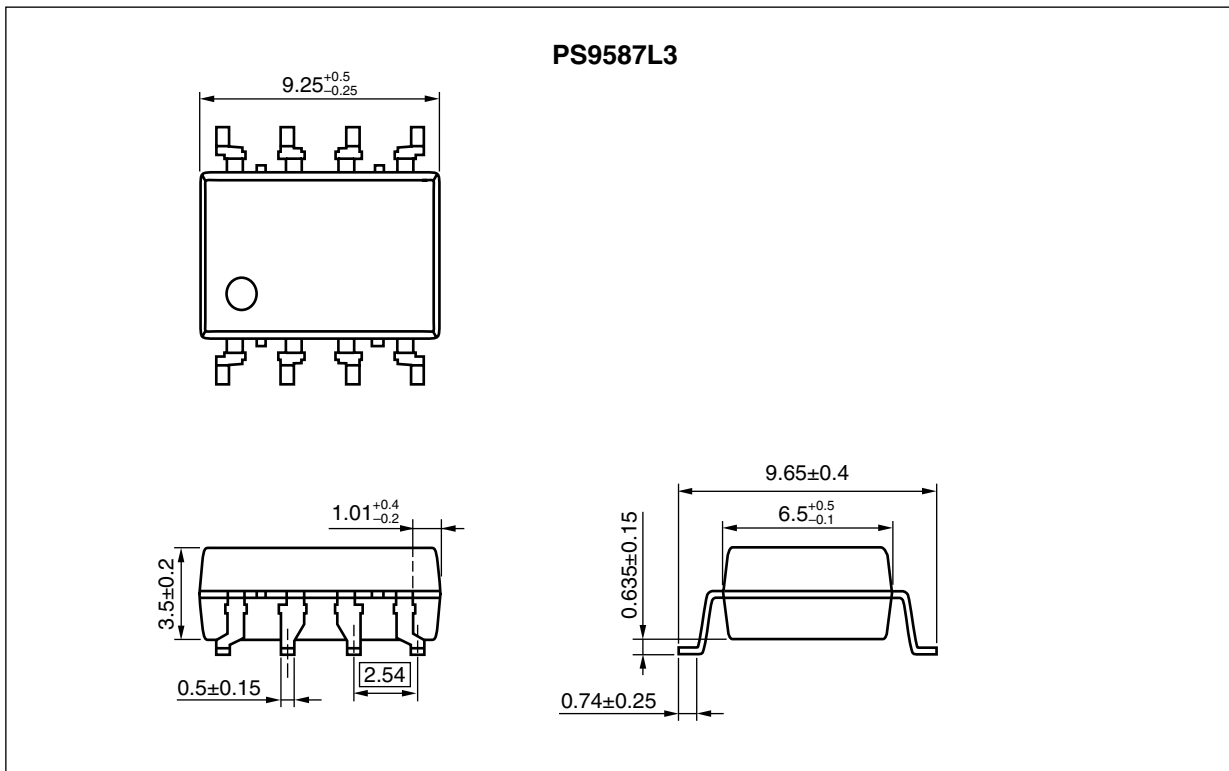
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PACKAGE DIMENSIONS (UNIT: mm)

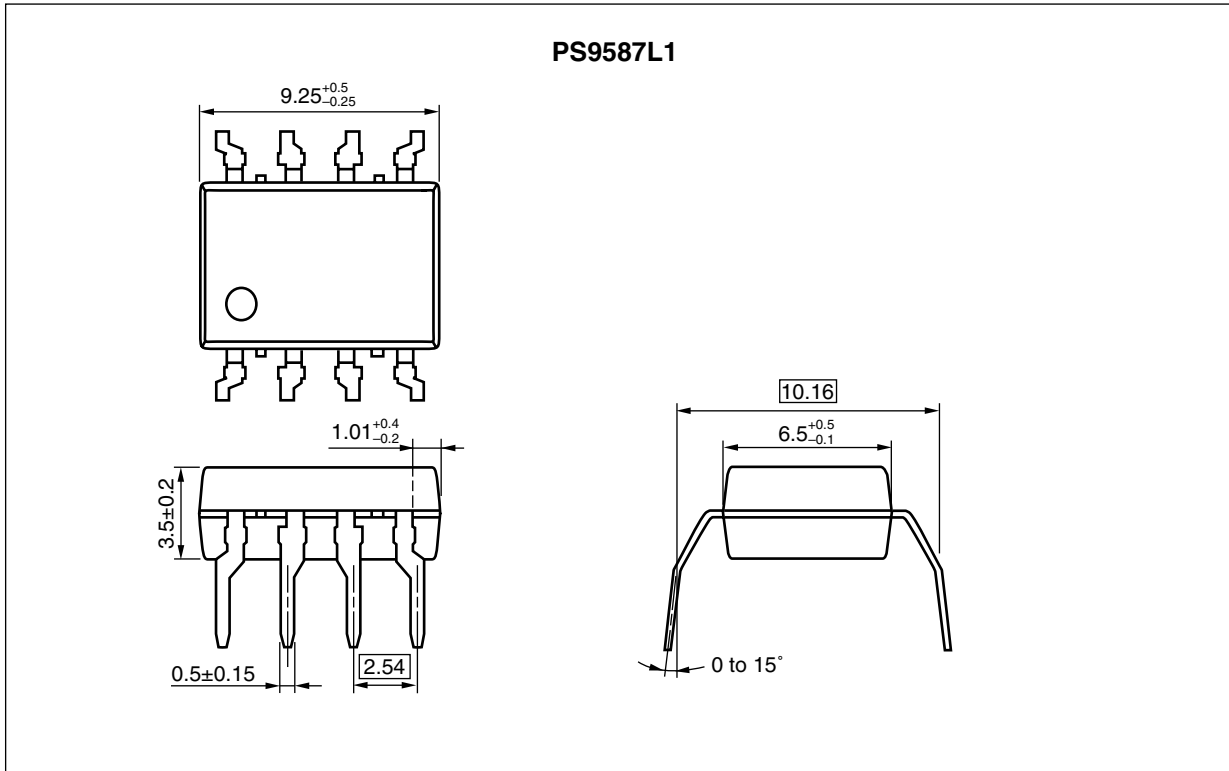
DIP Type



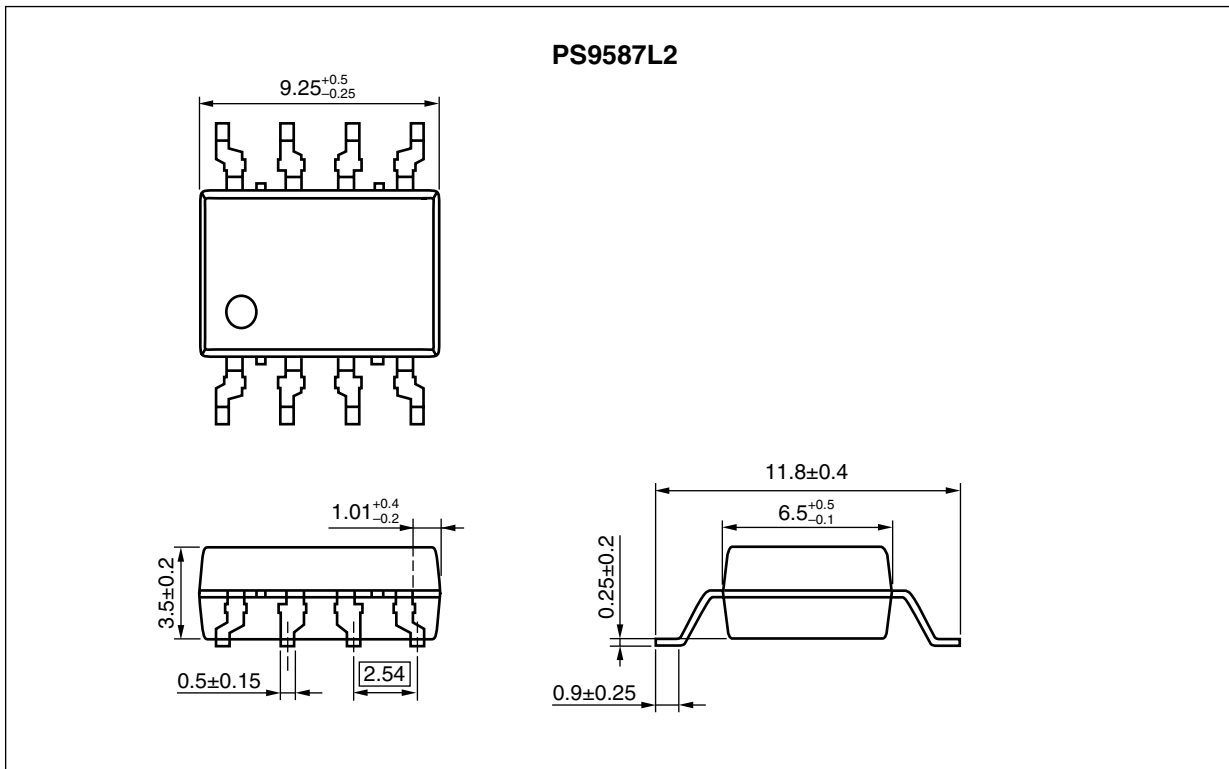
Lead Bending Type (Gull-wing) For Surface Mount



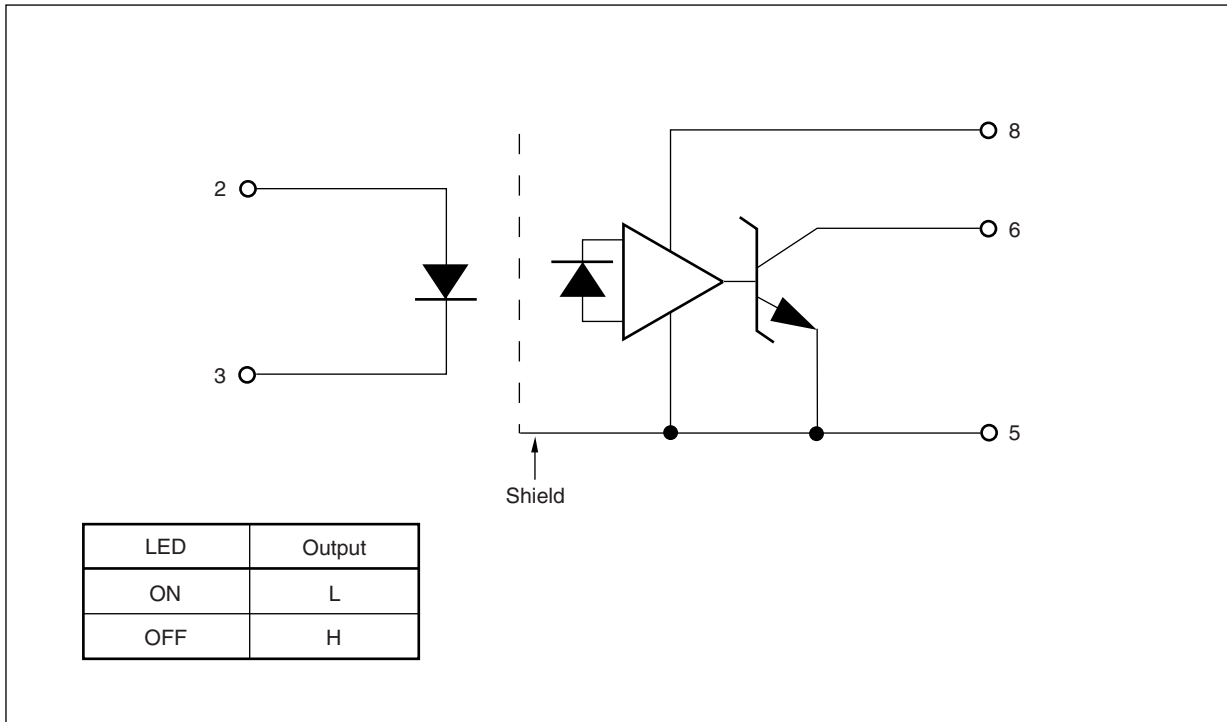
Lead Bending Type For Long Creepage Distance



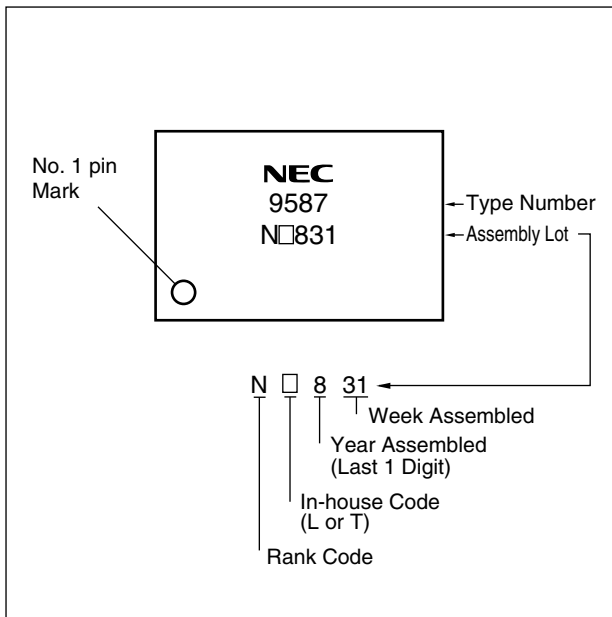
Lead Bending Type For Long Creepage Distance (Gull-wing) For Surface Mount



FUNCTIONAL DIAGRAM



<R> MARKING EXAMPLE



PHOTOCOUPLER CONSTRUCTION

Parameter	PS9587, PS9587L3	PS9587L1, PS9587L2
Air Distance (MIN.)	7 mm	8 mm
Outer Creepage Distance (MIN.)	7 mm	8 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number* ¹		
PS9587	PS9587-AX	Pb-Free (Ni/Pd/Au)	Magazine case 50 pcs	Standard products (UL, CSA, BSI, SEMKO, NEMKO, DEMKO, FIMKO approved)	PS9587		
PS9587L1	PS9587L1-AX				PS9587L1		
PS9587L2	PS9587L2-AX				PS9587L2		
PS9587L3	PS9587L3-AX				PS9587L3		
PS9587L2-E3	PS9587L2-E3-AX		Embossed Tape 1 000 pcs/reel		PS9587L2		
PS9587L3-E3	PS9587L3-E3-AX				PS9587L3		
PS9587-V	PS9587-V-AX		Magazine case 50 pcs	DIN EN60747-5-2 (VDE0884 Part2) Approved (Option)	PS9587		
PS9587L1-V	PS9587L1-V-AX				PS9587L1		
PS9587L2-V	PS9587L2-V-AX				PS9587L2		
PS9587L3-V	PS9587L3-V-AX				PS9587L3		
PS9587L2-V-E3	PS9587L2-V-E3-AX				Embossed Tape 1 000 pcs/reel		PS9587L2
PS9587L3-V-E3	PS9587L3-V-E3-AX						PS9587L3

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current ^{*1}	I _F	30	mA
	Reverse Voltage	V _R	5	V
Detector	Supply Voltage	V _{CC}	7	V
	Output Voltage	V _O	7	V
	Output Current	I _O	25	mA
	Power Dissipation ^{*2}	P _C	40	mW
Isolation Voltage ^{*3}		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T _A	-40 to +85	°C
Storage Temperature		T _{stg}	-55 to +125	°C

*1 Reduced to 0.3 mA/°C at T_A = 25°C or more.

*2 Applies to output pin V_O (Collector pin). Reduced to 1.5 mW/°C at T_A = 65°C or more.

*3 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.

Pins 1-4 shorted together, 5-8 shorted together.

RECOMMENDED OPERATING CONDITIONS (T_A = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
High Level Input Current	I _{FH}	6.3	10	12.0	mA
Low Level Input Voltage	V _{FL}	0		0.8	V
Supply Voltage	V _{CC}	4.5	5.0	5.5	V
TTL (R _L = 1 kΩ, loads)	N			5	
Pull-up Resistance	R _L	330		4 k	Ω

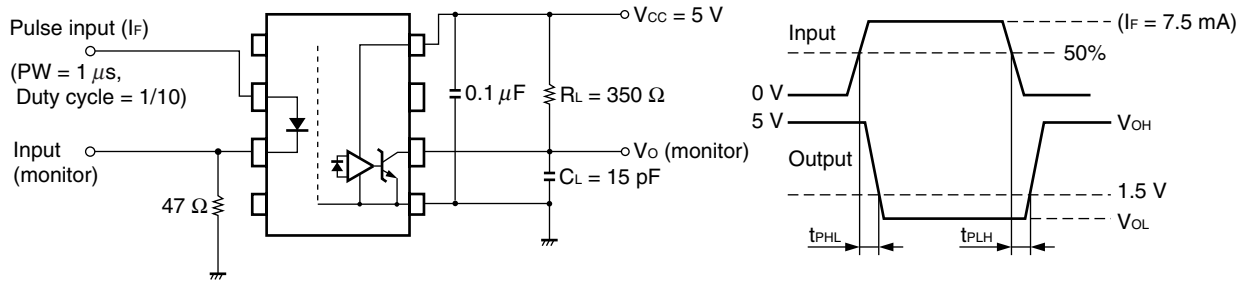
ELECTRICAL CHARACTERISTICS (T_A = -40 to +85°C, unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP. ¹⁾	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA, T _A = 25°C	1.4	1.65	1.8	V
	Reverse Current	I _R	V _R = 3 V, T _A = 25°C			10	μA
	Terminal Capacitance	C _t	V _F = 0 V, f = 1 MHz, T _A = 25°C		30	150	pF
Detector	High Level Output Current	I _{OH}	V _{CC} = V _O = 5.5 V, V _F = 0.8 V		1	100	μA
	Low Level Output Voltage ²⁾	V _{OL}	V _{CC} = 5.5 V, I _F = 5 mA, I _{OL} = 13 mA		0.2	0.6	V
	High Level Supply Current	I _{CCH}	V _{CC} = 5.5 V, I _F = 0 mA, V _O = Open		5	8	mA
	Low Level Supply Current	I _{CCL}	V _{CC} = 5.5 V, I _F = 10 mA, V _O = Open		9	11	mA
Coupled	Threshold Input Current (H → L)	I _{FHL}	T _A = 25°C			3.3	mA
			V _{CC} = 5 V, V _O = 0.8 V, R _L = 350 Ω		1.5	5	
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kV _{DC} , R _H = 40 to 60%, T _A = 25°C	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz, T _A = 25°C		0.9	5	pF
	Propagation Delay Time (H → L) ³⁾	t _{PHL}	V _{CC} = 5 V, T _A = 25°C V _{THHL} = V _{THLH} = 1.5 V,		35	75	ns
						100	
	Propagation Delay Time (L → H) ³⁾	t _{PLH}	R _L = 350 Ω, T _A = 25°C I _F = 7.5 mA, C _L = 15 pF		45	75	ns
						100	
	Rise Time	t _r			20		ns
	Fall Time	t _f			10		ns
Pulse Width Distortion (PWD) ³⁾	t _{PHL} -t _{PLH}			10	50	ns	
Propagation Delay Skew	t _{PSK}					60	ns
Common Mode Transient Immunity at High Level Output ⁴⁾	CM _H	V _{CC} = 5 V, T _A = 25°C, I _F = 0 mA, V _{O(MIN.)} = 2 V, V _{CM} = 1.5 kV, R _L = 350 Ω		15			kV/μs
Common Mode Transient Immunity at Low Level Output ⁴⁾	CM _L	V _{CC} = 5 V, T _A = 25°C, I _F = 7.5 mA, V _{O(MAX.)} = 0.8 V, V _{CM} = 1.5 kV, R _L = 350 Ω		15			kV/μs

*1 Typical values at $T_A = 25^\circ\text{C}$

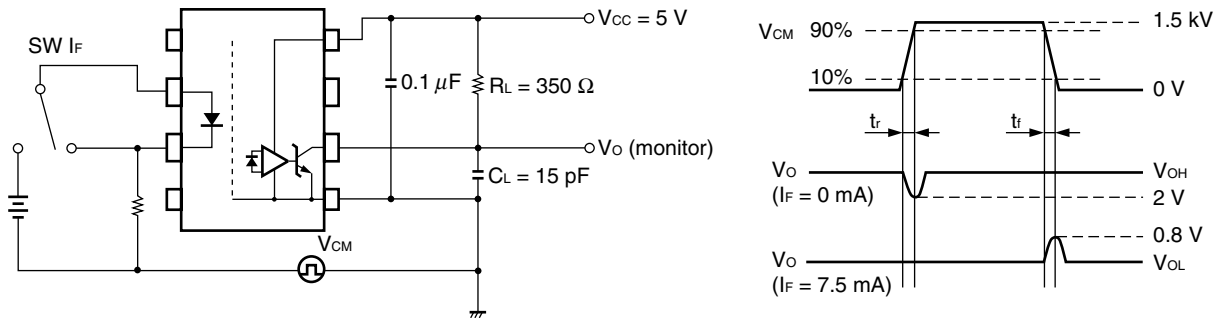
*2 Because V_{OL} of 2 V or more may be output when LED current is input and when output power supply is on and off, confirm the characteristics (operation with the power supply on and off) during design, before using this device.

*3 Test circuit for propagation delay time



Remark C_L includes probe and stray wiring capacitance.

*4 Test circuit for common mode transient immunity



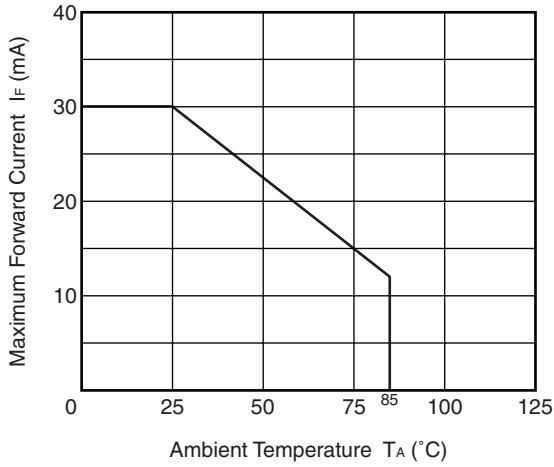
Remark C_L includes probe and stray wiring capacitance.

USAGE CAUTIONS

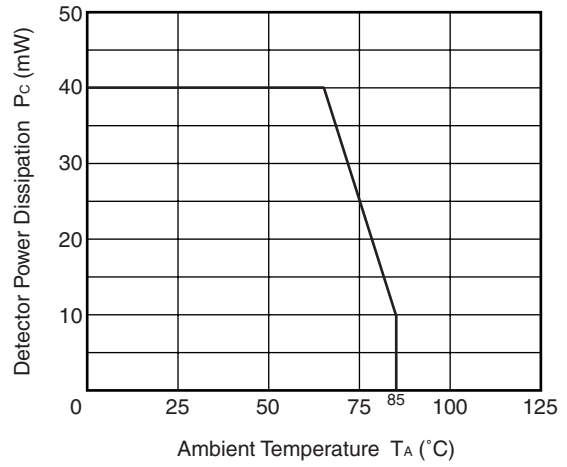
1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of more than $0.1\ \mu\text{F}$ is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
3. Avoid storage at a high temperature and high humidity.

TYPICAL CHARACTERISTICS (T_A = 25°C, unless otherwise specified)

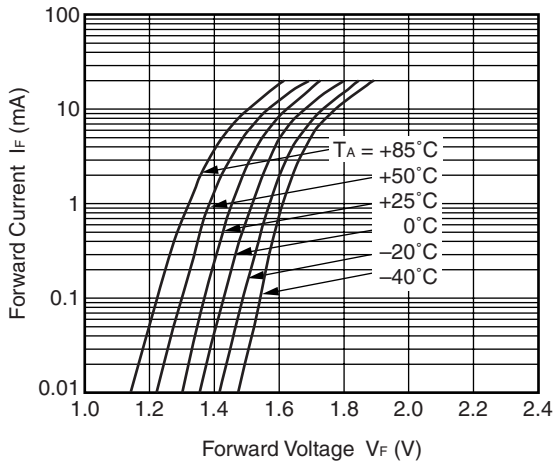
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



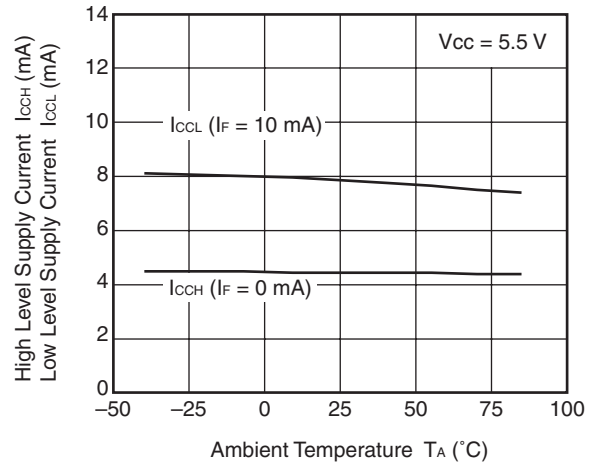
DETECTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



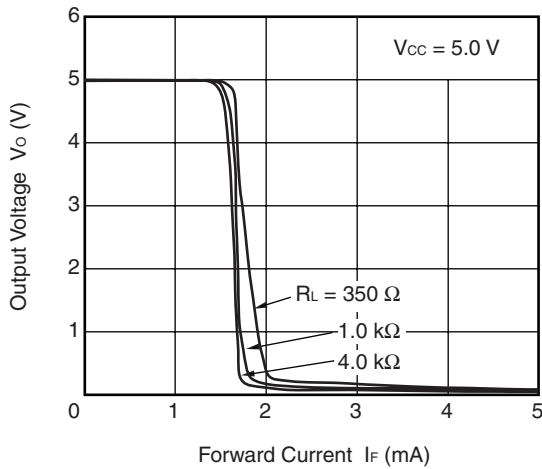
FORWARD CURRENT vs. FORWARD VOLTAGE



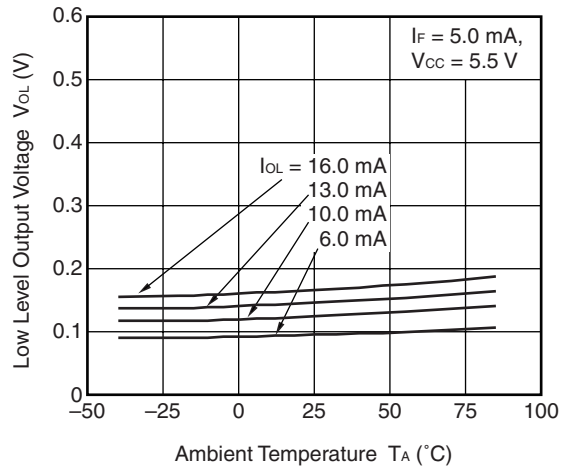
SUPPLY CURRENT vs. AMBIENT TEMPERATURE



OUTPUT VOLTAGE vs. FORWARD CURRENT

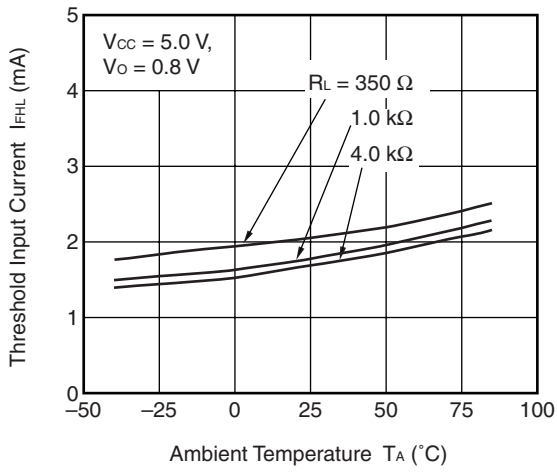


LOW LEVEL OUTPUT VOLTAGE vs. AMBIENT TEMPERATURE

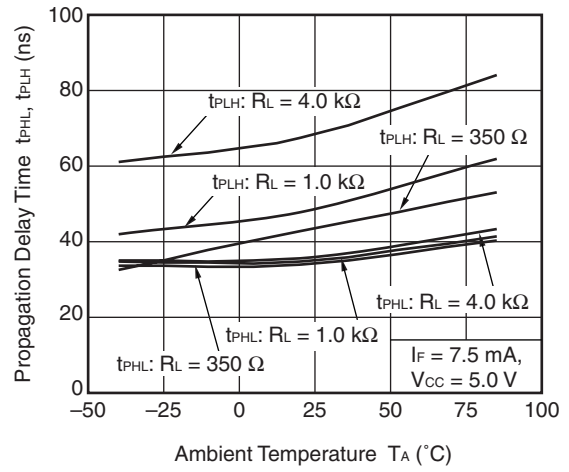


Remark The graphs indicate nominal characteristics.

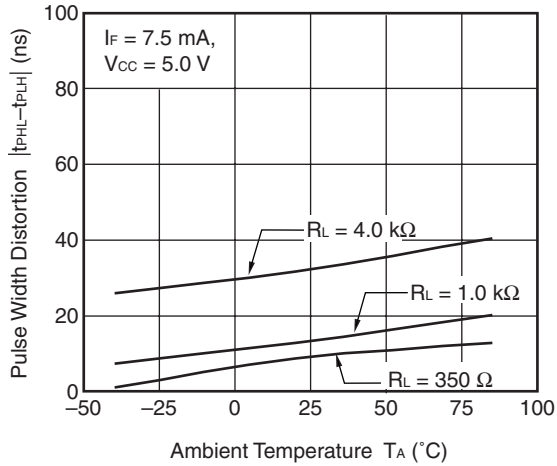
THRESHOLD INPUT CURRENT vs. AMBIENT TEMPERATURE



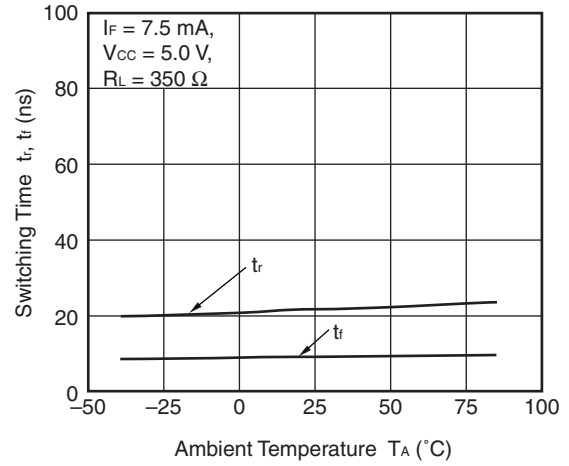
PROPAGATION DELAY TIME vs. AMBIENT TEMPERATURE



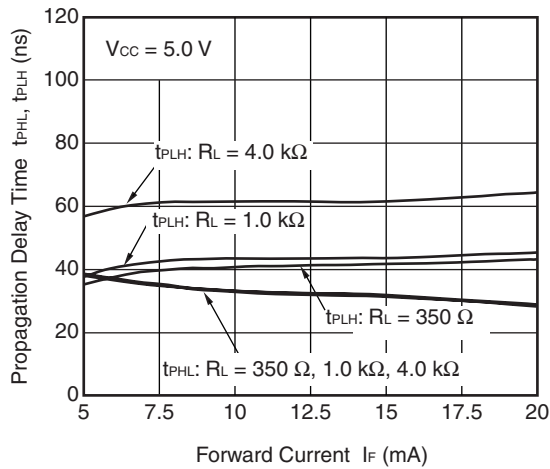
PULSE WIDTH DISTORTION vs. AMBIENT TEMPERATURE



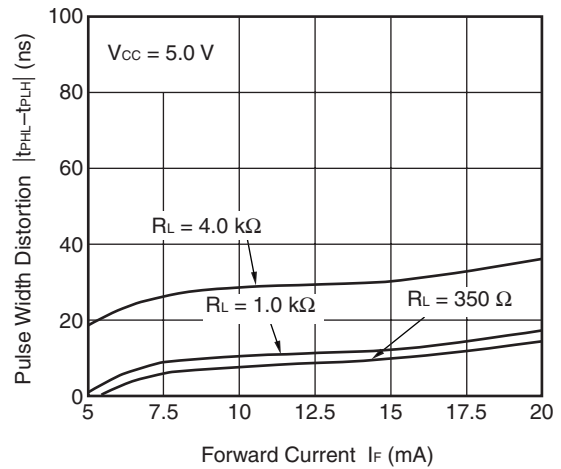
SWITCHING TIME vs. AMBIENT TEMPERATURE



PROPAGATION DELAY TIME vs. FORWARD CURRENT



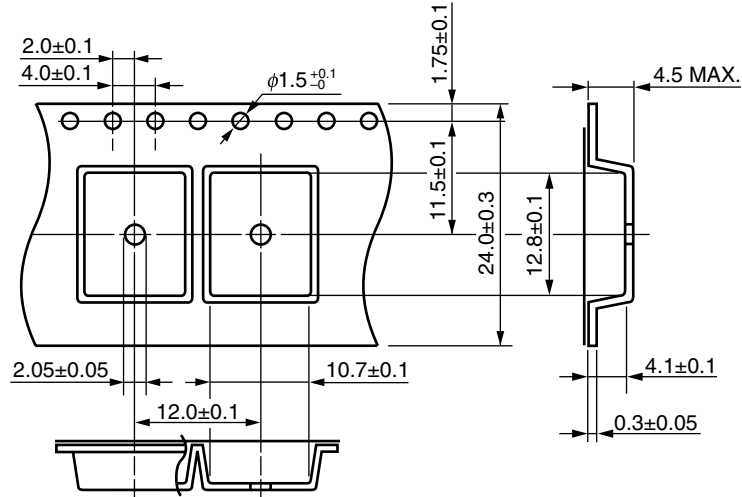
PULSE WIDTH DISTORTION vs. FORWARD CURRENT



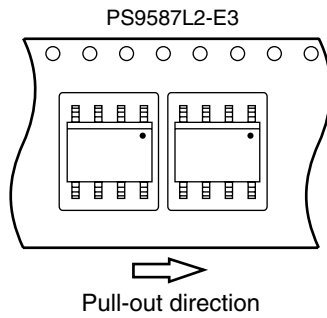
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

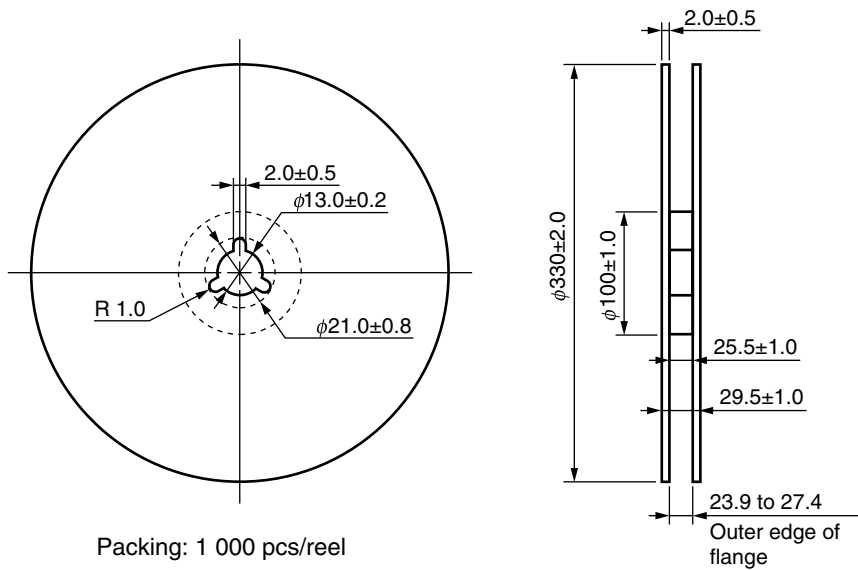
Outline and Dimensions (Tape)



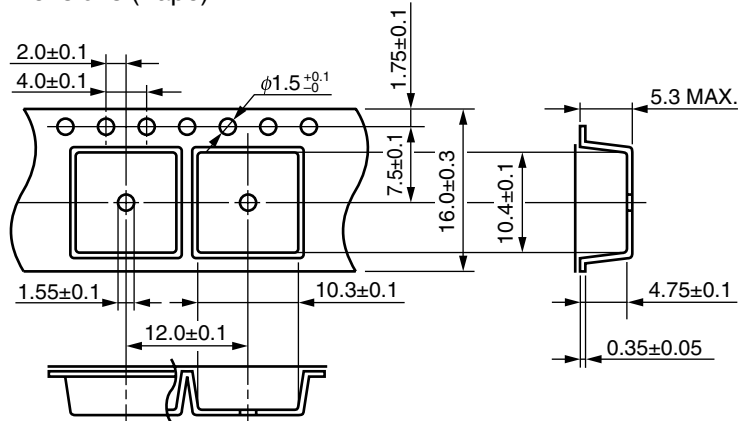
Tape Direction



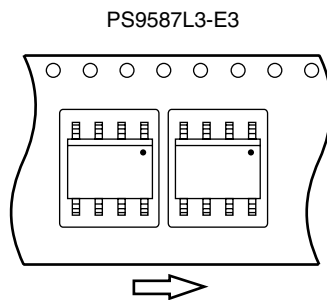
Outline and Dimensions (Reel)



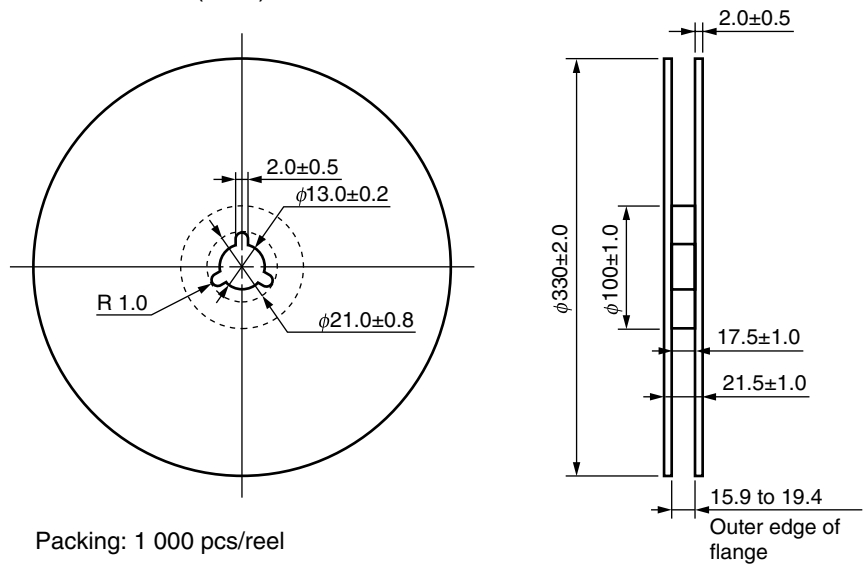
Outline and Dimensions (Tape)



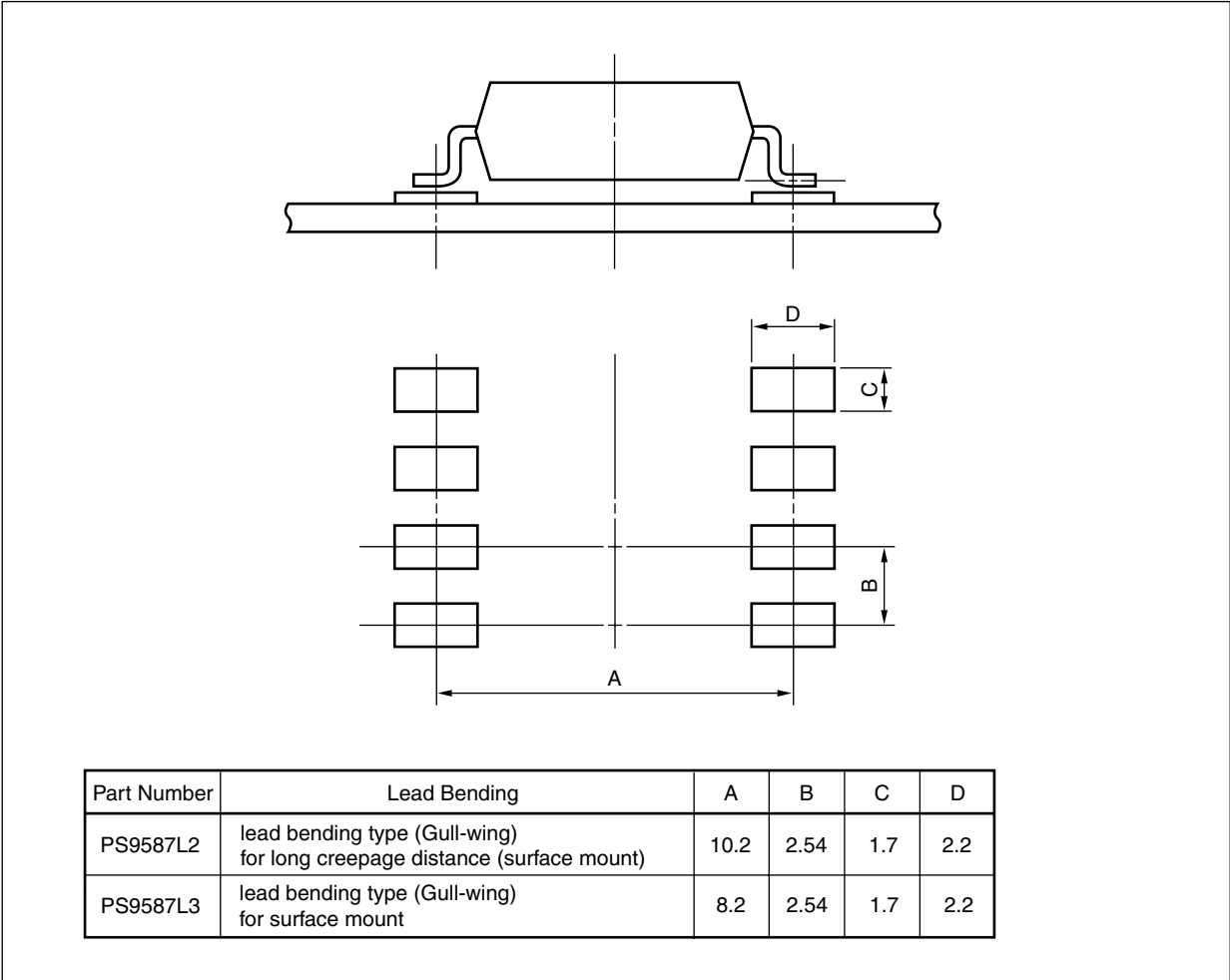
Tape Direction



Outline and Dimensions (Reel)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



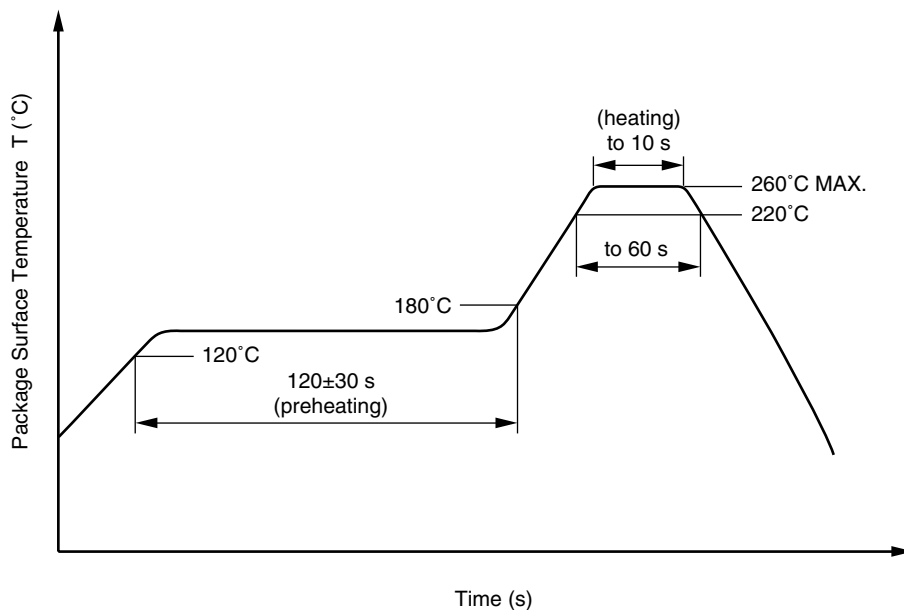
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

- Peak Temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(b) Please be sure that the temperature of the package would not be heated over 100°C

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

<R> USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Speck	Unit
Application classification (DIN EN 60664-1 VDE0110 Part 1) for rated line voltages ≤ 300 Vr.m.s. for rated line voltages ≤ 600 Vr.m.s.		IV III	
Climatic test class (DIN EN 60664-1 VDE0110)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.5 \times U_{IORM}$, $P_d < 5$ pC	U_{IORM} U_{pr}	1 130 1 695	V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}$, $P_d < 5$ pC	U_{pr}	2 119	V_{peak}
Highest permissible overvoltage	U_{TR}	8 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Clearance distance		>8.0	mm
Creepage distance		>8.0	mm
Comparative tracking index (DIN IEC 112/VDE 0303 Part 1)	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	T_{stg}	-55 to +125	$^{\circ}C$
Operating temperature range	T_A	-40 to +85	$^{\circ}C$
Isolation resistance, minimum value $V_{IO} = 500$ V dc at $T_A = 25^{\circ}C$ $V_{IO} = 500$ V dc at T_A MAX. at least $100^{\circ}C$	Ris MIN. Ris MIN.	10^{12} 10^{11}	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I_F , $P_{si} = 0$) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500$ V dc at $T_A = T_{si}$	T_{si} I_{si} P_{si} Ris MIN.	175 400 700 10^9	$^{\circ}C$ mA mW Ω

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<p>Caution GaAs Products</p>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. <ol style="list-style-type: none"> 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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